

ABSTRACT

This invention relates to novel electrically conductive adhesives for solder replacement in electronics packaging applications. More specifically, the present invention relates to novel electrically conductive adhesives, which are fabricated with epoxide-modified polyurethane (EPU) resins and show superior impact performance. The electrically
5 conductive adhesive includes an epoxide-modified polyurethane resin, a cross-linking agent, an adhesion promoter and a conductive filler. The adhesive can optionally include one or more of an epoxy resin, a catalyst, and a diluent.